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(54) Title: POLISHING COMPOSITIONS AND METHODS OF USE THEREOF

(57) Abstract: This disclosure relates to polishing compositions containing at least one abrasive, at least one polymer removal enhancer, and at least one solvent. The polishing compositions of this disclosure may optionally include at least one of a cationic surfactant, an azole-containing corrosion inhibitor, or a nonionic surfactant. The polishing compositions of this disclosure may polish a polymeric substrate at a rate of at least about 200 Å/min.



WO 2025/019194 A2